



SYMBOL	MILLIMETERS		
	MIN.	NOM.	MAX.
A	<i>↗</i>	2.25	2.60
A ₁	0.40	0.50	0.60
D/E	31.00 BSC		
D ₁ /E ₁	29.00 REF		
e	1.00 BSC		
φb	0.50	0.60	0.70
aaa	<i>↗</i>	<i>↗</i>	0.20
ccc	<i>↗</i>	<i>↗</i>	0.35
ddd	<i>↗</i>	<i>↗</i>	0.25
eee	<i>↗</i>	<i>↗</i>	0.10
M	30		

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034-AAN-1

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
03/12/09	1.3	Removed note 3 regarding component land diameter. This dimension is specified in UG112 , Device Package User Guide under Recommended PCB Design Rules.
11/12/09	1.4	Changed symbol ddd value from 0.30 to 0.25 to conform to JEDEC MS-034.

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